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(12) **United States Design Patent** (10) **Patent No.:** **US D798,830 S**
Anzai et al. (45) **Date of Patent:** **** *Oct. 3, 2017**

(54) **COOLING DEVICE FOR AN ELECTRONIC COMPONENT HEAT SINK**

F28D 15/02; F28F 1/30; F28F 2215/00;
G06F 1/20

See application file for complete search history.

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(73) Assignee: **NIPPON LIGHT METAL COMPANY, LTD**, Tokyo (JP)

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/566,046**

(Continued)

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Primary Examiner — Jennifer Rivard

Assistant Examiner — April Rivas

(30) **Foreign Application Priority Data**

(74) *Attorney, Agent, or Firm* — Oliff PLC

Dec. 4, 2015 (JP) 2015-027261

(51) **LOC (10) Cl.** **13-03**

(57) **CLAIM**

The ornamental design for a cooling device for an electronic component heat sink, as shown and described.

(52) **U.S. Cl.**

USPC **D13/179**

DESCRIPTION

(58) **Field of Classification Search**

USPC D13/179, 122, 182; D23/415, 330
CPC .. H05K 7/20; H05K 7/20172; H05K 7/20127;
H05K 7/20336; H05K 7/20154; H05K
7/20272; H01L 23/34; H01L 23/3672;
H01L 23/40; H01L 23/4006; H01L
23/4093; H01L 23/427; H01L 23/46;
F28D 15/0275; F28D 1/426; F28D
1/0426; F28D 15/0208; F28D 15/04;

FIG. 1 is a front, bottom, left-side perspective view of a cooling device for an electronic component heat sink showing our new design, the front, top, left-side being a mirror image thereof;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a right-side elevational view thereof;
FIG. 5 is a left-side elevational view thereof;
FIG. 6 is an enlarged view of an area shown in a dashed line box labeled "6" in FIG. 2; and,

(Continued)

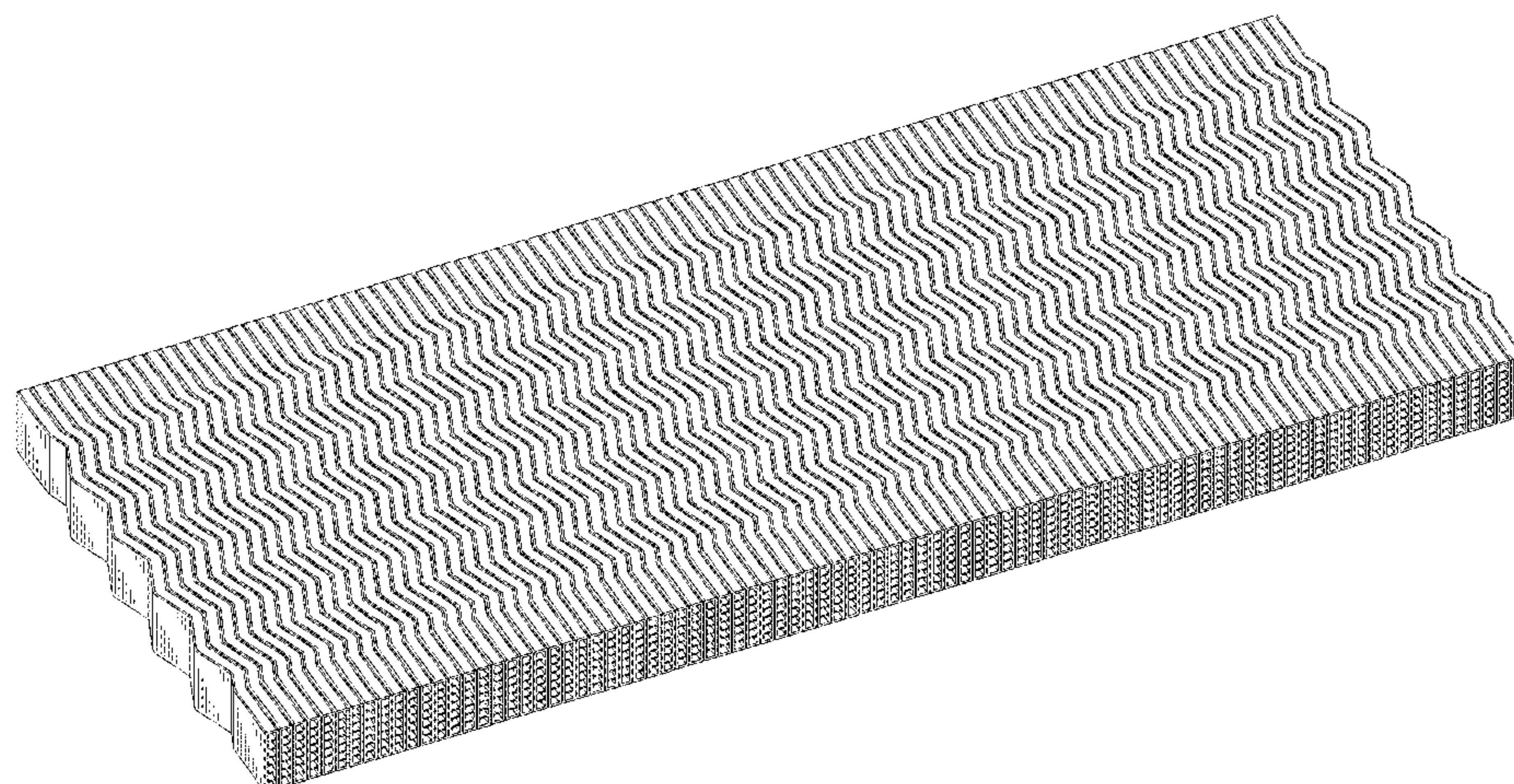


FIG. 7 is an enlarged view of an area shown in a dashed line box labeled "7" in FIG. 3. The dashed line boxes identify areas that are enlarged, and form no part of the claimed design.

1 Claim, 6 Drawing Sheets

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FIG. 1

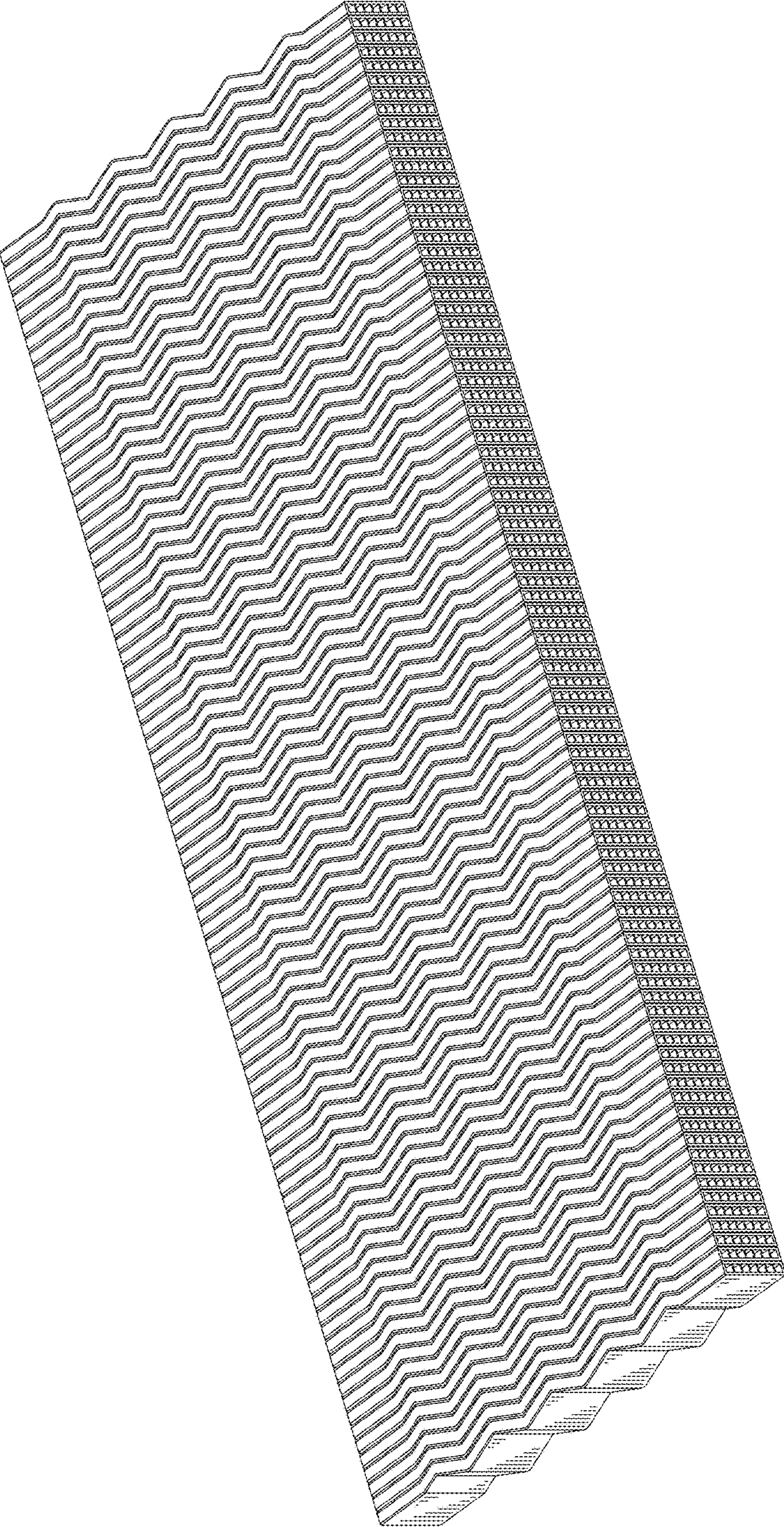


FIG. 2

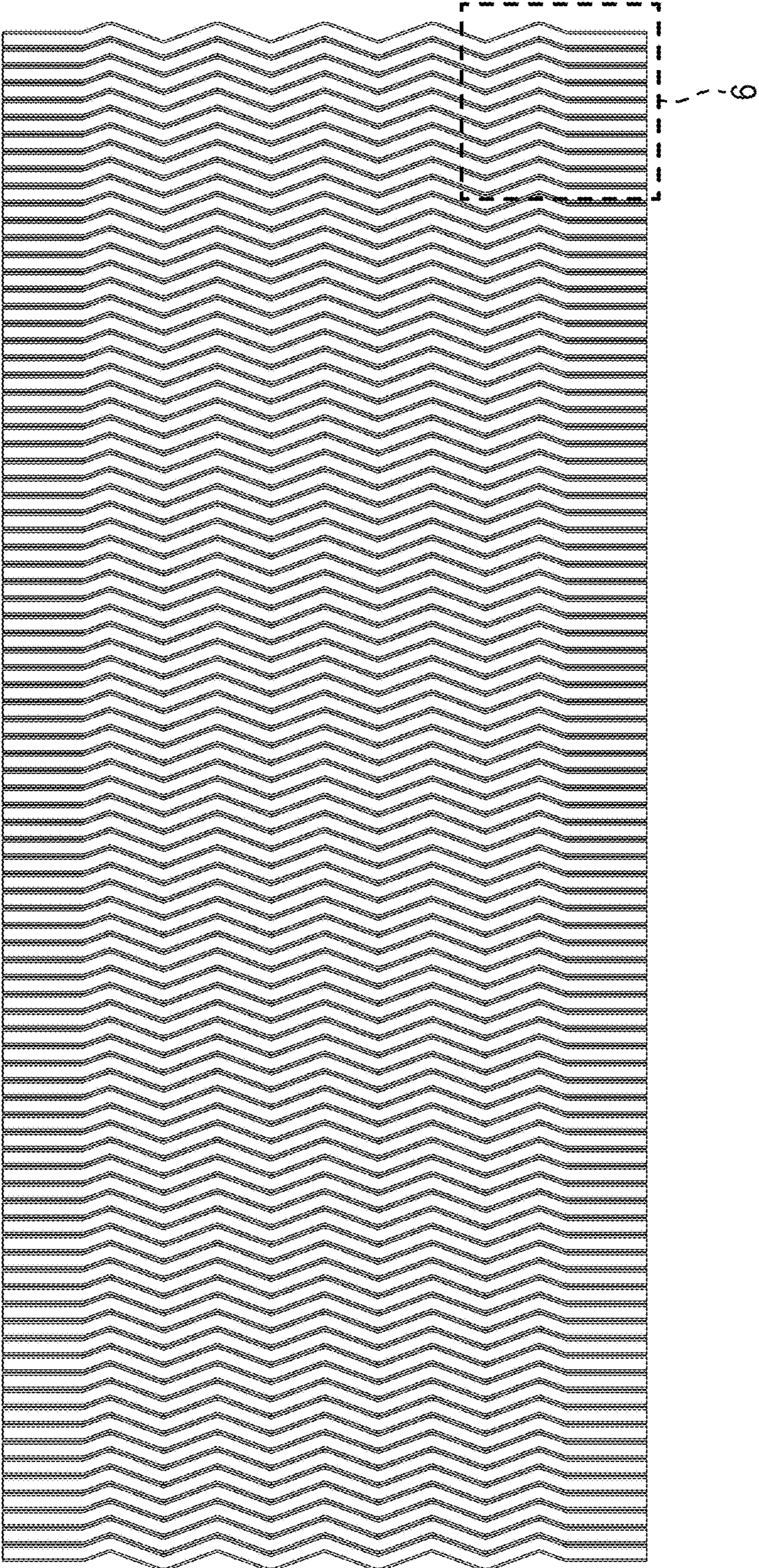


FIG. 3

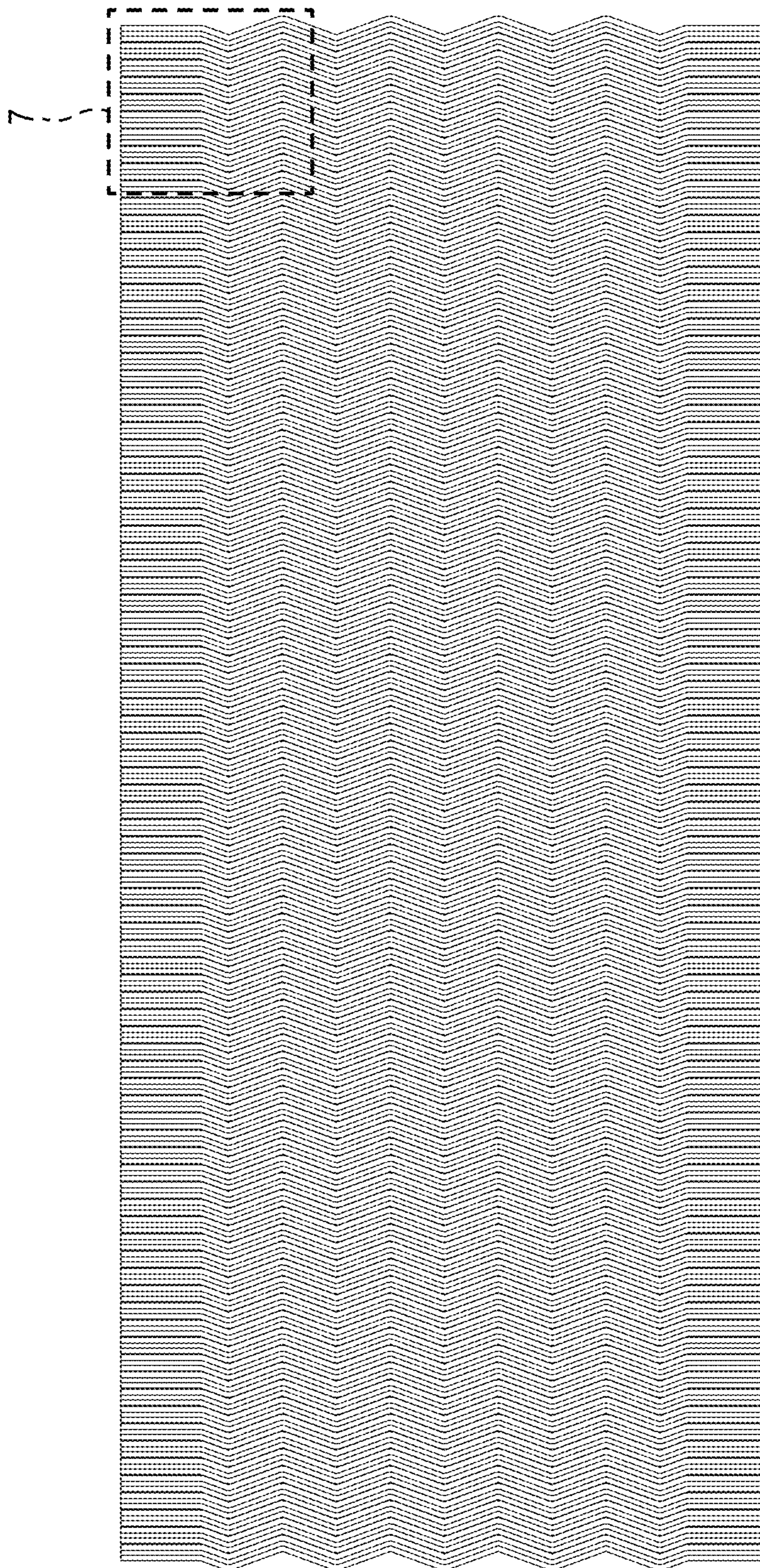


FIG. 4

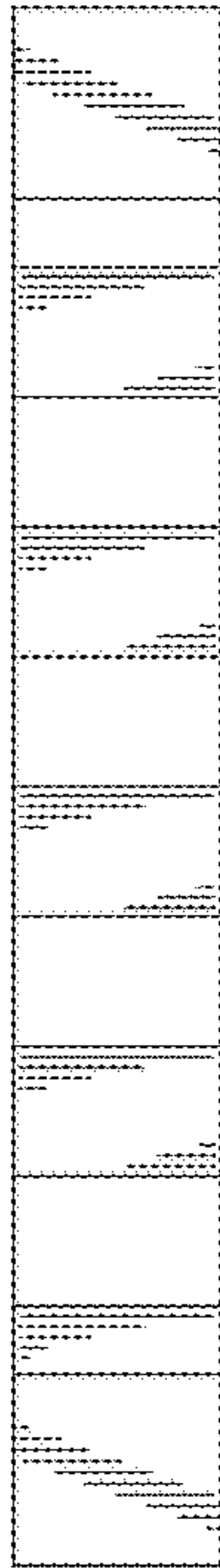
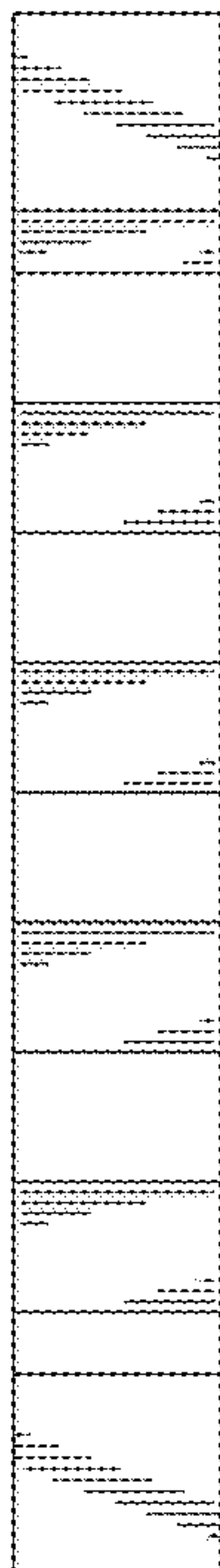


FIG. 5



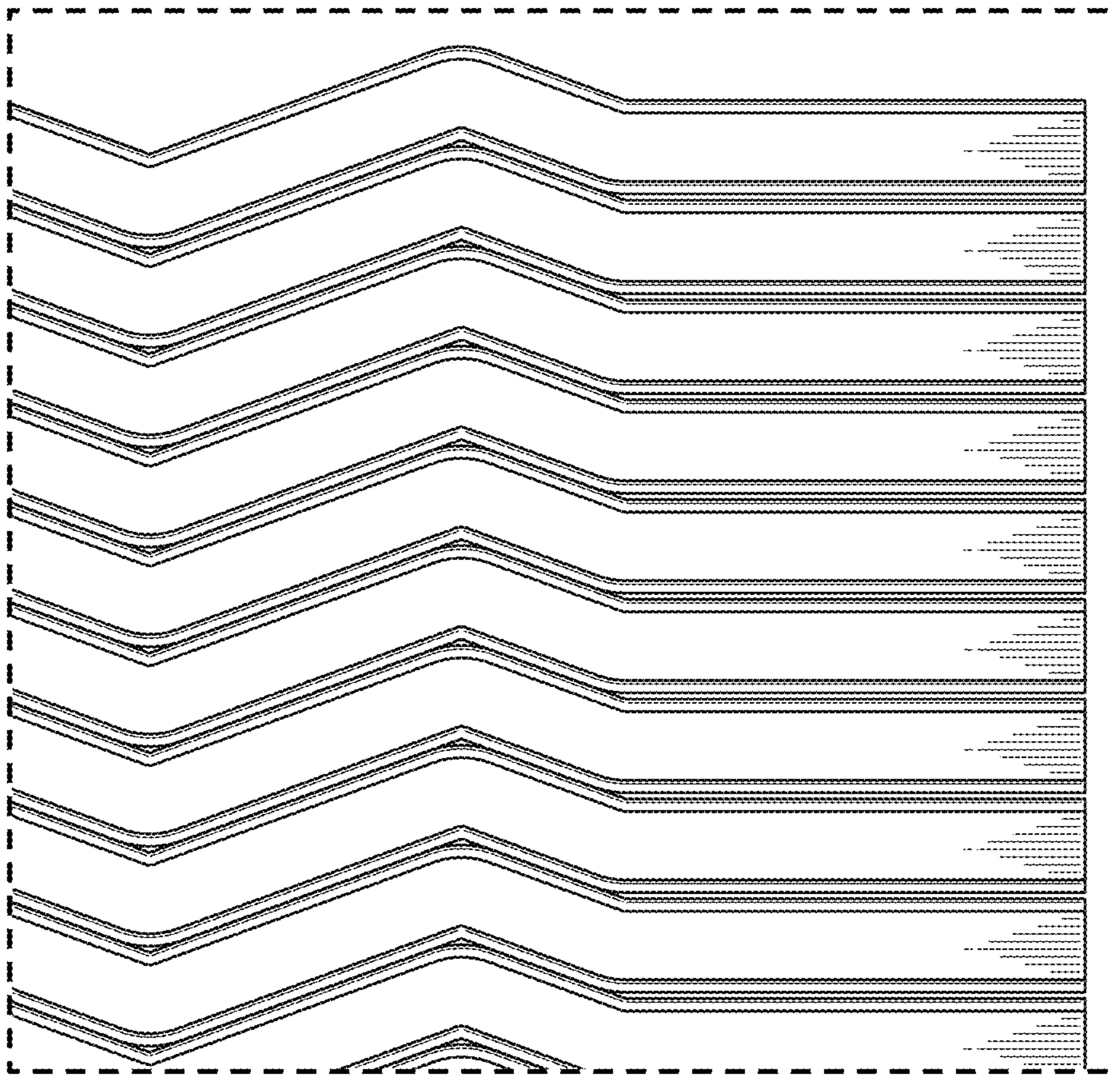


FIG. 6

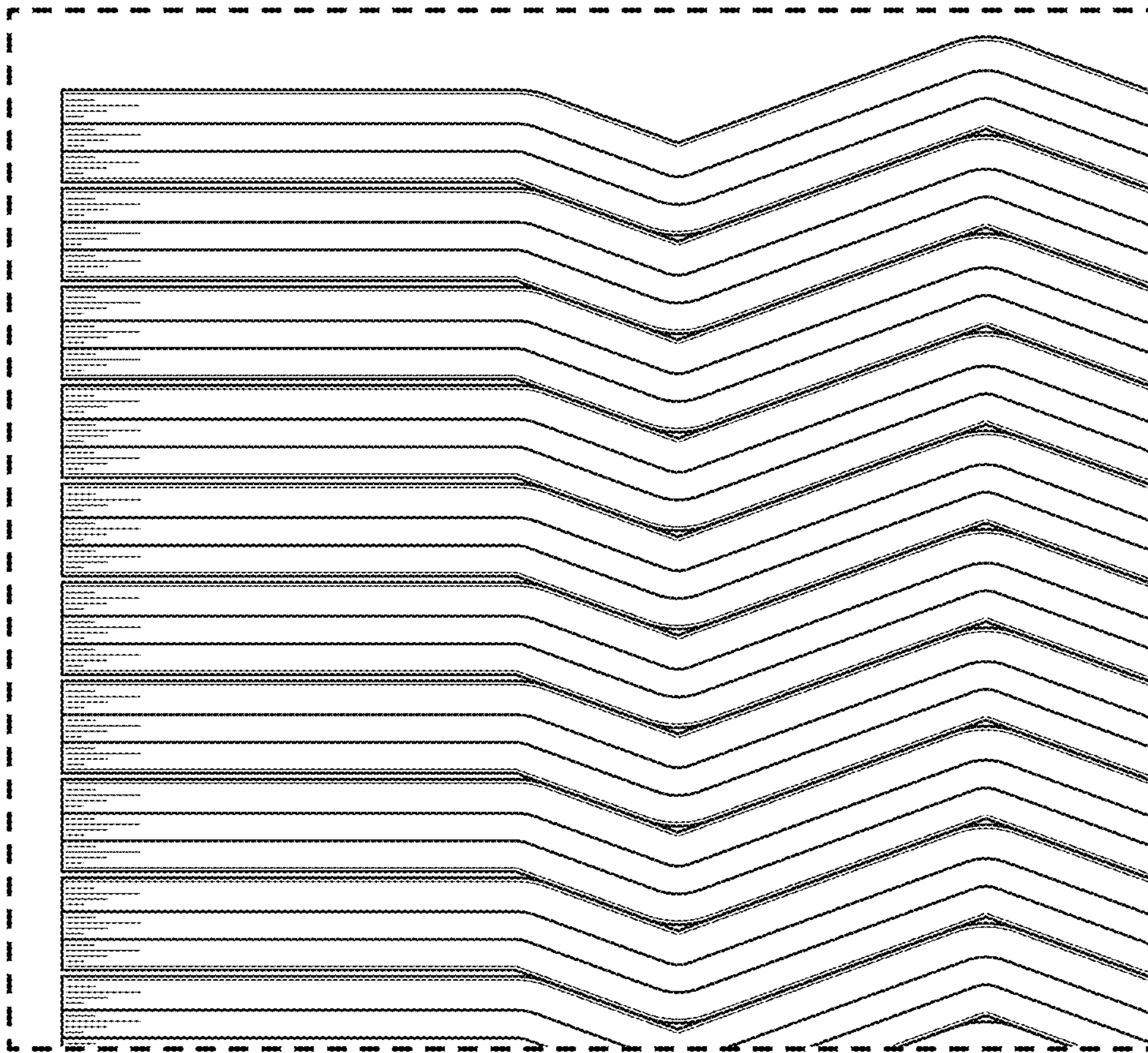


FIG. 7